Texas Instruments 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140926001
Qualification of DFAB as an Additional Fab Site Option for TLC5928PWPxx devices
Change Notification / Sample Request

Date: 9/29/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140926001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLC5928PWP	null
TLC5928PWPR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140926001	**PCN Date:**	09/29/2014

Title:	Qualification of DFAB as an Additional Fab Site Option for TLC5928PWPxx devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

***Proposed 1st Ship Date:**	12/29/2014	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the qualification of DFAB as an additional fab site option for TLC5928PWPxx devices. These devices are listed in "Product Affected" section.

Current Fabs	**New (Qualified) Fab**
Site, process, wafer dia.	**Site, process, wafer dia.**
CFAB, LBC4, 150mm	**DFAB, LBC4, 200mm**

The LBC4 process is mature and has been successfully running in production since 2001. Qualification details are provided in the Qual Data Section.

Process/Site Qualification	**Qualification Date**
LBC4 Process/DFAB	2/23/2001

Reason for Change:

Continuity of Supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
CFAB	CU3	CHN
HU-BIP-4	HOU	USA

New

Chip Site	**Chip site code (20L)**	**Chip country code (21L)**
DL-LIN	**DLN**	**USA**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750
(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLC5928PWP	TLC5928PWPR	TLC5928PWPRG4

LBC4 Process Qualification

Qualification Data: (Approved: 2001)

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qual Vehicle: SN104969VFP

Wafer Fab Site:	DFAB	Wafer Fab Process:	LBC4
Wafer Fab Process:	LBC4	Wafer Diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fails Lot#1	Lot#2	Lot#3
**Life Test	155C (240hrs)	116/0	116/0	116/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, (96 Hrs)	77/0	77/0	77/0
**Thermal Shock	-65/+150C (500 Cycles)	77/0	77/0	77/0
ESD HBM	2000V	3/0	-	-
ESD CDM	1500V	3/0	-	-
Electrical Characterization	-	Pass	Pass	Pass
Latch-up	(per JESD78)	6/0	6/0	6/0
Manufacturability (Wafer Fab)	Per site spec	Approved	-	-
Manufacturability (Assembly)	(per mfg. Site specification)	Approved	-	-
X-Ray	Top View Only	5/0	5/0	5/0
Visual/Mechanical		Pass	Pass	Pass
**High Temp. Storage Bake	170C (420 Hrs)	45/0	45/0	45/0

**Preconditioning: Level 2-260C

Qual Vehicle: TPS54671/ TPS79733			
Wafer Fab Site:	DFAB	Wafer Fab Process:	LBC4
Wafer Fab Process:	LBC4	Wafer Diameter:	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fails Lot#1	 Lot#2	 Lot#3
**Life Test	155C (240hrs)	116/0	116/0	116/0
**Thermal Shock	-65/+150C (500 Cycles)	77/0	77/0	-
ESD HBM	2000V	3/0	3/0	3/0
ESD CDM	1000V	3/0	3/0	3/0
Electrical Characterization	-	Pass	Pass	Pass
Bond Strength		76/0	76/0	76/0
Die Shear		5/0	5/0	5/0
Latch-up	(per JESD78)	5/0	5/0	5/0
Manufacturability (Wafer Fab)	Per site spec	Approved	-	-
Manufacturability (Assembly)	(per mfg. Site specification)	Approved	-	-
Wafer Level Reliability		Approved	-	-
**Preconditioning: Level 1-235C				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com